FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. ESLABS.003A	APPLICATION NO. 09/593,587
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (USE SEVERAL SHEETS IF NECESSARY)	APPLICANT Knowles, et al.	
	FILING DATE 06/13/00	GROUP 3743

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)
JF	1	2,542,637	2/20/51	~~Method of Rectifying a Neutral Salt Heat-Treating Bath~~ DE POY	148	15	
	2	3,294,880	12/27/66	~~Continuous Method of Manufacturing Ablative and Refractory Materials~~ TURKAT	264	29	
	3	3,375,308	3/26/68	~~Method of Making High Purity and Non-Melting~~ Filaments TURKAT	264	29	
	4	3,531,249	9/29/70	~~Pyrolytic Graphite Filaments~~ TURKAT	23	209.2	
	5	3,543,842	12/1/70	~~Device for Elastic and Heat Conducting Connection~~ of Thermo-Couples MERGES	165	82	
	6	3,609,992	10/5/71	~~Hermetically Sealed Box for Maintaining a~~ Semiconductor Radiation Detector at a ~~Very~~ Low ~~Temperature~~ CACHEUX	62	514	
	7	3,969,754	7/13/76	~~Semiconductor Device Having~~ Supporting Electrode ~~Composite Structure of Metal Containing Fibers~~ KUNIYA ET AL.	~~357~~	~~65~~	
	8	4,161,747	7/17/79	~~Shock Isolator for Operating a Diode Laser on a~~ Closed-Cycle Refrigerator JENNINGS	~~357~~	~~83~~	
	9	4,318,954	3/9/82	~~Printed Wiring Board Substrates for Ceramic Chip Carriers~~ JENSEN	428	209	
	10	4,414,142	11/8/83	~~Organic Matrix Composites Reinforced with~~ Intercalated ~~Graphite~~ VOGEL ET AL.	252	506	
	11	4,415,025	11/15/83	~~Thermal Conduction Element for Semiconductor Devices~~ HORVATH	165	185	
	12	4,424,145	1/3/84	~~Calcium Intercalated Boronated Carbon Fiber~~ SARA	252	509	
	13	4,435,375	3/6/84	~~Method for Producing a Carbon Filament and Derivatives Thereof~~ TAMURA ETAL.	423	439	
	14	4,470,063	9/4/84	~~Copper Matrix Electrode Having Carbon Fibers Therein~~ ARAKAWA ET AL.	~~357~~	~~67~~	
	15	4,482,912	11/13/84	~~Stacked Structure Having matrix-Fibered Composite Layers and a Metal Layer~~ CHIBA ET AL.	~~357~~	~~67~~	
	16	4,485,429	11/27/84	~~Apparatus for Cooling Integrated Circuit Chips~~ MITTAL	361	386	
	17	4,591,659	5/27/86	~~Multilayer Printed Circuit Board Structure~~ LIEBOWITZ	174	68.5	
	18	4,630,174	12/16/86	Circuit ~~Package with External Circuit Board and Connection~~ KAUFMAN	361	388	
	19	4,749,514	6/7/88	~~Graphite Intercalation Compound Film and Method of Preparing the Same~~ MURAKAMI ETAL.	252	500	
	20	4,816,289	3/28/89	Process for Production of a Carbon Filament KOMATSU ET AL.	423	447.3	
	21	4,849,858	7/18/89	~~Composite Heat Transfer Means~~ GRAPES ETAL.	361	388	
	22	4,867,235	9/19/89	~~Composite Heat Transfer Means~~ GRAPES ET AL	165	185	

EXAMINER Jonal A Jr.	DATE CONSIDERED 9/5/02

*EXAMINER: INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED. INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.

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	23	4,878,152	10/31/89	Mounting for Printed Circuits Forming a Heat Sink with Controlled Expansion	361	386	
	24	4,933,804	6/12/90	Interference Suppression for Semi-Conducting Switching Devices	361	111	
	25	4,966,226	10/30/90	Composite Graphite Heat Pipe Apparatus and Method	165	104.26	
	26	4,985,805	1/15/91	Device for the Cooling of Optoelectronic Components and Use of a Flange Joint Used Thereof	361	386	
	27	5,014,161	5/7/91	System for Detachably Mounting Semiconductors on Conductor Substrate	361	388	
	28	5,077,637	12/31/91	Solid State Directional Thermal Cable	361	386	
	29	5,111,359	5/5/92	Heat Transfer Device and Method	361	388	
	30	5,150,748	9/29/92	Advanced Survivable Radiator	165	41	
	31	5,212,625	5/18/93	Semiconductor Module Having Projecting Cooling Fin Groups	361	383	
	32	5,224,030	6/29/93	Semiconductor Cooling Apparatus	361	386	
	33	5,260,124	11/9/93	Intercalated Hybrid Graphite Fiber Composite	428	257	
	34	5,287,248	2/15/94	Metal Matrix Composite Heat Transfer Device and Method	361	708	
	35	5,316,080	5/31/94	Heat Transfer Device	165	185	
	36	5,323,294	6/21/94	Liquid Metal Heat Conducting Member and Integrated Circuit Package Incorporating Same	361	699	
	37	5,389,400	2/14/95	Method for Making a Diamond/Carbon/Carbon Composite Useful as an Integral Dielectric Heat Sink	427	249	
	38	5,402,004	3/28/95	Heat Transfer Module for Ultra High Density and Silicon on Silicon Packaging Applications	357	717	
	39	5,424,916	6/13/95	Combination Conductive and Convective Heatsink	361	698	
	40	5,428,601	1/9/96	Method and Device for the Production of Carbon Nanotubes	204	173	
	41	5,494,753	2/27/96	Articles Having Thermal Conductors of Graphite	428	408	
	42	5,520,976	5/28/96	Composite Enclosure for Electronic Hardware	428	36.3	
	43	5,523,260	6/4/96	Method for Heatsinking a Controlled Collapse Chip Connection Device	437	209	
	44	5,542,471	8/6/96	Heat Transfer Element Having the Thermally Conductive Fibers	165	170	
*	45	5,566,752	10/22/96	High Heat Density Transfer Device	165	185	
	46	5,591,312	1/7/97	Process for Making Fullerene Fibers	204	157.41	

EXAMINER	DATE CONSIDERED
	9/5/02

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* previously cited on PTO-892

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	47	5,604,037	2/18/97	~~Diamond/Carbon/Carbon Composite Useful as an Integral Dielectric Heat Sink~~	428	408	
	48	5,608,267	3/4/97	~~Molded Plastic Semiconductor Package Including~~ Heat ~~Spreader~~	257	796	
	49	5,753,088	5/19/98	~~Method for Making Carbon Nanotubes~~	204	173	
	50	5,814,290	9/29/98	~~Silicon Nitride Nanowhiskers and Method of Making Same~~	423	344	
	51	5,830,326	11/3/98	~~Graphite Filaments Having Tubular Structure and Method of Forming the Same~~	204	173	
	52	6,063,243	5/16/00	~~Method for Making Nanotubes and Nanoparticles~~	204	164	

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO

EXAMINER INITIAL		OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)
	1	Ren, et al., Synthesis of Large Arrays of Well-Aligned Carbon Nanotubes on Glass, SCIENCE, Vol. 282, pp. 105-107, November 6, 1988
	2	Huang, et al., Growth of Highly Oriented Carbon Nanotubes of Plasma-Enhanced Hot Filament Chemical Vapor Deposition, APPLIED PHYSICS LETTERS, Vol. 73, No. 6, pp. 3845-3847, December 28, 1998
	3	Li, et al., Highly-ordered Carbon Nanotube Arrays for Electronics Applications, APPLIED PHYSICS LETTERS, Vol. 75, No. 3, pp. 367-369, July 19, 1999

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EXAMINER Howard A Fries	DATE CONSIDERED 9/5/02

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